

A universal concept able to accommodate different package types, size, pitch & thickness with minimal change
A solution able to minimize the development costs and to shorten the lead time due to a "high mix low volume" product. A solution able to support both burn-in & validation test.

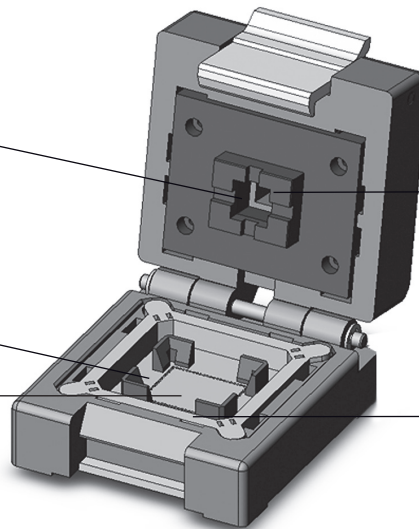
Custom sockets are also available for products below

SERIES IC561 (CLAMSHELL - CMT)

Opening for air flow
to the package (5.5 x 5.5mm)

Drilled array plate for any package pitches
700 pins max. Pitch 0.30mm min.

Suitable packages
BGA / CSP / LGA / QFN / SON

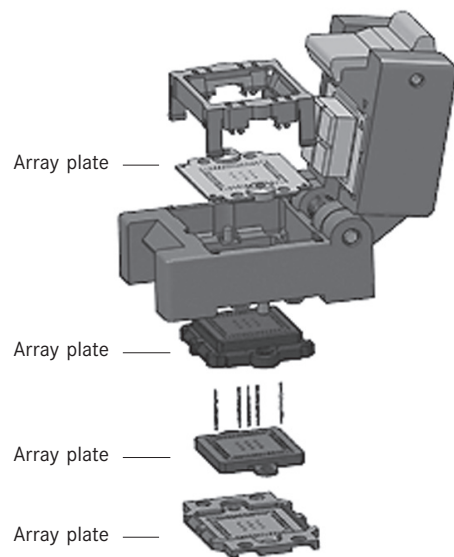


Shared clamp for different package size and thickness.

Package body thickness from 0.5 to 1.3mm
Enough Touch down zone to package.

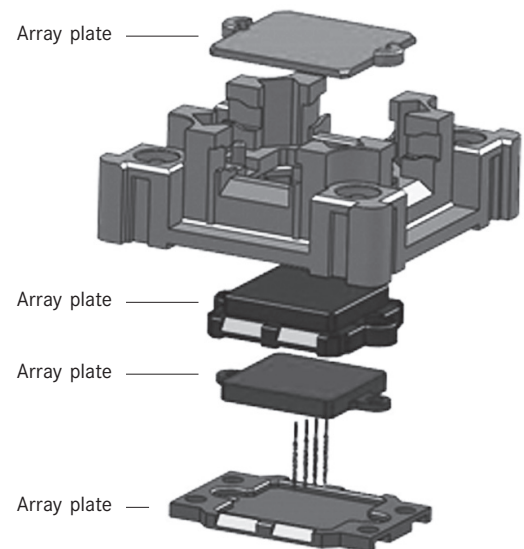
Separate guide for different package sizes in order to reduce the tooling cost.
From 10 x 10 to 18 x 18mm

SERIES IC564 (CLAMSHELL - CMT)



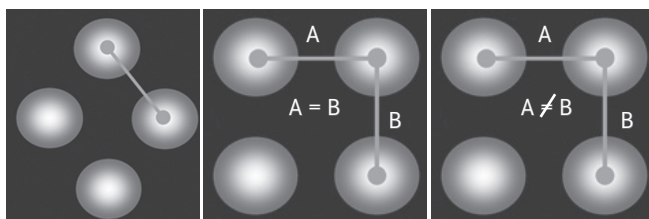
INFO:
The related array plates can be use
for both
IC564 and IC584 series

SERIES IC584 (OPEN TOP - CMT)



PITCH CAPABILITY

Pitch capability: 0.40mm min. (IC561)
0.30mm min. (IC564 / NP584)
Package size capability: 2.0 ~ 10.0 mm
Package thickness capability : 0.5 ~ 1.3 mm

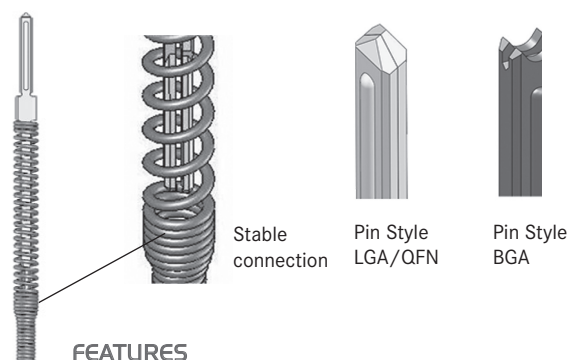


Staggered
Pitch

Regular
Pitch

Irregular
Pitch

2-PART PROBE PINS



FEATURES

- Inexpensive (low cost)
- Cost saving for compression mount technology (CMT)
- New design concept by reduction of the number of components (2 parts)

SERIES IC561, IC564 AND NP584

SPECIFICATIONS

| | |
|------------------------|--|
| Insulation Resistance: | 1,000MΩ or more at 100V DC |
| Contact Force: | From ~0.137N (14gf) to ~ 0.226N (23gf) / pin ~ 0.1226N (23gf) / per pin (IC564 / NP564) |
| Operating Temp.Range: | -55°C to +150°C |
| Mating Cycles: | 10,000 insertions min. |

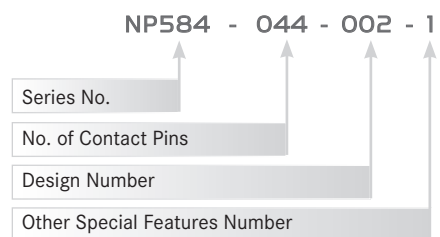
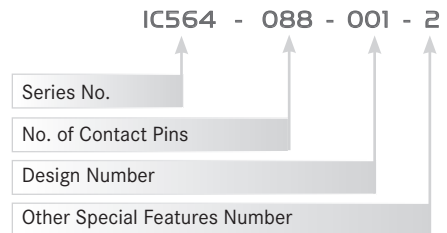
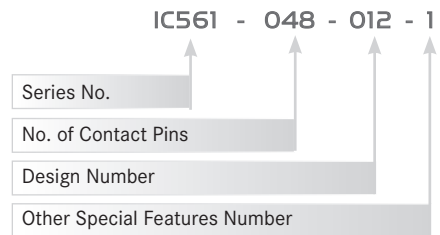
MATERIALS AND FINISH

| | |
|-----------|---|
| Housing: | Polyester (PES), glass-filled Polyetherimide (PEI), glass-filled |
| Contacts: | Beryllium Copper (BeCu) |
| Plating: | Gold over Nickel |

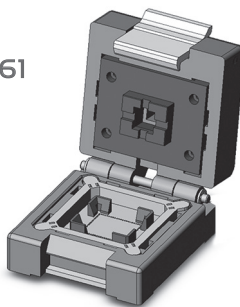
FEATURES

- Semi custom socket suitable for BGA, CSP, QFN, SON, LGA packages
- Dimensions from 2x2 to 15x15 mm sq. (rectangle to MAX 14.5x16.5)
- Pitch from 0.30mm standard, staggered or irregular
- Spring loader pusher
- Airflow through top duct channel
- One outline for all packages
- Compression mount for quick installation and maintenance
- Full flexibility through drilled insulator and milled pusher
- Low cost with respect to a full custom solution

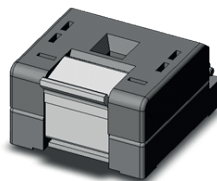
PART NUMBER (EXAMPLES)



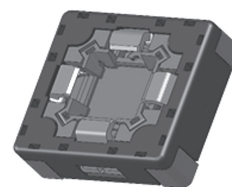
IC561



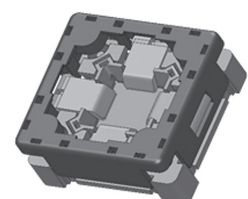
IC564



NP584

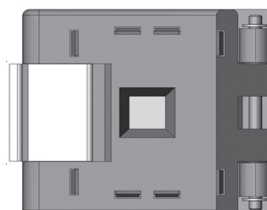


actuated



not actuated (DUT)

Body size 38.0 x 35.0



Body size 20.5 x 28.8



Body size 28.0 x 28.0

